



Micron Technology, Inc.  
Quality & Reliability Assurance Dept  
Mail Stop 502  
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Boise, Idaho 83707-0006

RE: RoHS Certification

Micron Technology, Inc. certifies that our Pb-free die/wafer and component level products meet the requirements of the current DIRECTIVE 2011/65/EU and 2015/863/EU, a.k.a. Restriction of Hazardous Substances (RoHS) Directive (Recast) without exemptions. Micron's Pb-free products mentioned above contain less than the following amounts of the RoHS banned substances:

- Less than 0.1% Lead – Pb
- Less than 0.1 % Mercury – Hg
- Less than 0.01 % Cadmium – Cd
- Less than 0.1 % Hexavalent Chromium – Cr(VI)
- Less than 0.1 % Polybrominated Biphenyls - PBB
- Less than 0.1 % Polybrominated Diphenyl Ethers – PBDE
- Less than 0.1 % Decabromodiphenyl Ether – DecaBDE
- Less than 0.1 % Bis(2 - ethylhexyl) phthalate / Di - 2 - ethylhexyl phthalate - DEHP
- Less than 0.1 % Butyl benzyl phthalate -BBP
- Less than 0.1 % Dibutylphthalate - DBP
- Less than 0.1 % Diisobutyl phthalate - DIBP

Please note that our module level products do contain electronic ceramic passive parts that may use lead or lead-oxides which are exempt from Directive 2011/65/EU (see Article 4, Annex III of the Annex thereto).

The information provided above, applies to all Micron products, including part number NAND512W3A2SNXE.

Further questions should be addressed to your local Micron sales representative.

Micron Technology, Inc.  
Global Supply Chain Compliance Department